

Thin Film Mini-MELF Resistors



SMM 0204 thin film MELF resistors are the perfect choice for most fields of modern professional electronics where reliability and stability are of major concern. The typical applications in the fields of automotive, industrial and medical equipment reflect the outstanding level of proven reliability.

FEATURES

- Advanced metal film technology
- AEC-Q200 qualified
- Approval acc. EN 140401-803 available on request
- Excellent stability in different environmental conditions
- Best in class pulse load capability
- Sulfur resistance verified according to ASTM B 809
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

 AUTOMOTIVE
GRADE

RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

APPLICATIONS

- Automotive
- Telecommunication
- Industrial
- Medical equipment

TECHNICAL SPECIFICATIONS	
DESCRIPTION	SMM0204
DIN size	0204
Metric CECC size	RC 3715M
Resistance range	0.22 Ω to 10 MΩ
Resistance tolerance	± 5 %; ± 1 %; ± 0.5 %; ± 0.25 %; ± 0.1 %
Temperature coefficient	± 100 ppm/K; ± 50 ppm/K; ± 25 ppm/K; ± 15 ppm/K
Rated dissipation $P_{70}^{(1)}$	0.4 W
Operating voltage, U_{max} AC/DC	200 V
Operating temperature range	-55 °C to 155 °C
Permissible voltage against ambient (insulation): 1 min; U_{ins}	300 V
Failure rate: FIT _{observed}	≤ 0.1 x 10 ⁻⁹ /h
Zero-Ohm-Resistor: OMM0204	$R_{max} = 10 \text{ m}\Omega$; $I_{max} = 3 \text{ A}$

Notes

- The IECQ-CECC approved product versions SMM0204 EN803 E0 and OMM0204 EN803 E0 respectively feature a quality factor $\pi_Q = 3$ for the purpose of system MTBF calculations, compared with $\pi_Q = 10$ for the standard versions.
- (1) Please refer to APPLICATION INFORMATION below.

APPLICATION INFORMATION

The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials may be required to maintain the reliability of the assembly.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime. At the maximum permissible film temperature of 155 °C the useful lifetime is specified for 8000 h. The designer may estimate the performance of the particular resistor application or set certain load and temperature limits in order to maintain a desired stability.



MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION				
OPERATION MODE		PRECISION	STANDARD	POWER
Rated dissipation, P_{70}	SMM0204	0.07 W	0.25 W	0.4 W
Operating temperature range		-10 °C to 85 °C	-55 °C to 125 °C	-55 °C to 155 °C
Permissible film temperature, $\vartheta_{F \max}$		85 °C	125 °C	155 °C
Max. resistance change at P_{70} for resistance range, $\Delta R/R$ after:	SMM0204	10 Ω to 1 M Ω	0.22 Ω to 1 M Ω	0.22 Ω to 10 M Ω
	1000 h	≤ 0.05 %	≤ 0.15 %	≤ 0.25 %
	8000 h	≤ 0.1 %	≤ 0.3 %	≤ 0.5 %
	225 000 h	≤ 0.25 %	≤ 0.75 %	-

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE				
TYPE / SIZE	TCR	TOLERANCE	RESISTANCE	E-SERIES
SMM0204	± 100 ppm/K	± 5 %	0.22 Ω to 10 M Ω	E24
	± 50 ppm/K	± 1 %	0.82 Ω to 10 M Ω	E24; E96
		± 0.5 %	10 Ω to 1 M Ω	E24; E96; E192
	± 25 ppm/K	± 0.5 %	10 Ω to 1 M Ω	E24; E96; E192
		± 0.25 %	22 Ω to 511 k Ω	
		± 0.1 %	43 Ω to 511 k Ω	
	± 15 ppm/K	± 0.5 %	10 Ω to 221 k Ω	E24; E96; E192
		± 0.25 %	22 Ω to 221 k Ω	
		± 0.1 %	43 Ω to 221 k Ω	
	Jumper		≤ 10 m Ω ; $I_{\max} = 3$ A	

Notes

- The color of the body coating is light green for jumpers and for a temperature coefficient of ± 50 ppm/K or of ± 100 ppm/K, pink for ± 25 ppm/K, or violet for ± 15 ppm/K.
- Zero ohm jumper are marked with one centered black band.

PACKAGING						
TYPE / SIZE	CODE	QUANTITY	CARRIER TAPE	WIDTH	PITCH	REEL DIAMETER
SMM0204 OMM0204	B1 ⁽¹⁾	1000 ⁽¹⁾	Antistatic blister tape acc. IEC 60286-3 Type 2a	8 mm	4 mm	180 mm/7"
	B3	3000				330 mm/13"
	B0	10 000				
SMM0204 EN803 E0 OMM0204 EN803 E0	B1	1000	Antistatic blister tape acc. IEC 60286-3 Type 2a	8 mm	4 mm	180 mm/7"
	B3	3000				330 mm/13"
	B0	10 000				

Note

- ⁽¹⁾ Package of 1000 pieces, code B1, is available only for products with TCR ± 25 ppm/K or ± 15 ppm/K, and with tolerance ± 0.25 % or ± 0.1 %. Bulk case acc. IEC 60286-6 available on request.



PART NUMBER AND PRODUCT DESCRIPTION																	
Part Number: SMM02040C5620FB000																	
Part Number: SMM0204VC5620FB000																	
Part Number: OMM02040000000B000																	
S	M	M	0	2	0	4	0	C	5	6	2	0	F	B	0	0	0
O	M	M	0	2	0	4	0	0	0	0	0	0	0	B	0	0	0
TYPE / SIZE		VERSION				TCR			RESISTANCE				TOLERANCE		PACKAGING		
SMM0204 OMM0204		0 = Neutral V = EN 140401-803, version A, nominal failure rate level E0				E = ± 15 ppm/K D = ± 25 ppm/K C = ± 50 ppm/K B = ± 100 ppm/K 0 = Jumper			3 digit value 1 digit multiplier 0000 = Jumper MULTIPLIER 7 = *10 ⁻³ 2 = *10 ² 8 = *10 ⁻² 3 = *10 ³ 9 = *10 ⁻¹ 4 = *10 ⁴ 0 = *10 ⁰ 5 = *10 ⁵ 1 = *10 ¹				B = ± 0.1 % C = ± 0.25 % D = ± 0.5 % F = ± 1 % J = ± 5 % 0 = Jumper		B1 B3 B0		
Product Description: SMM0204 50 562R 1 % B0																	
Product Description: SMM0204 50 562R 1 % B0 EN803 E0																	
Product Description: OMM0204 0R0 B0																	
SMM0204		50				562R			1 %				B0		-		
OMM0204		-				0R0			-				B0		-		
TYPE / SIZE		TCR				RESISTANCE			TOLERANCE				PACKAGING		VERSION		
SMM0204 OMM0204		± 15 ppm/K ± 25 ppm/K ± 50 ppm/K ± 100 ppm/K				100R = 100 Ω 2M21 = 2.21 MΩ 0R0 = JUMPER			± 0.1 % ± 0.25 % ± 0.5 % ± 1 % ± 5 %				B1 B3 B0				

Notes

- Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION.
- Products according to EN 140401-803 can be ordered by using the related ordering code "SMM0204V...".



DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade ceramic body (Al_2O_3) and conditioned to achieve the desired temperature coefficient. Nickel plated steel termination caps are firmly pressed on the metallized rods. A special laser is used to achieve the target value by smoothly cutting a helical groove in the resistive layer without damaging the ceramic. The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel and copper plating for enhanced temperature cycling stability. Four or five color code rings designate the resistance value and tolerance in accordance with **IEC 60062** ⁽¹⁾.

The result of the determined production is verified by an extensive testing procedure performed on 100 % of the individual resistors. This includes full screening for the elimination of products with a potential risk of early field failures (feasible for $R \geq 10 \Omega$) according to EN 140401-803, 2.1.2.2. Only accepted products are laid directly into the blister tape in accordance with **IEC 60286-3, Type 2a** ⁽¹⁾.

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapor phase as shown in **IEC 61760-1** ⁽¹⁾. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.

The resistors are completely lead (Pb)-free, the pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes. Solderability is specified for 2 years after production or requalification, however, excellent solderability is proven after extended storage in excess of 10 years. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven under extensive testing.

All products comply with the **IEC 62474**, Material Declaration for Products of and for the Electrotechnical Industry.

The dedicated database ⁽²⁾, that list declarable substances, ensures full compliance with the following directives:

- 2000/53/EC End of Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the use of Hazardous Substances Directive (RoHS)
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

APPROVALS

The resistors are qualified according to AEC-Q200. Resistors approved according to EN 140401-803 are available by using the related ordering code.

RELATED PRODUCTS

MELF resistors of other sizes are available:

Thin Film Micro-MELF Resistors SMM0102
(www.vishay.com/doc?20003)

Thin Film MELF Resistors SMM0207
(www.vishay.com/doc?20005)

Resistors are available with established reliability in accordance with **EN 140401-803 Version E**. Please refer to datasheet "MELF Resistors with Established Reliability" (www.vishay.com/doc?28707).

MS1 ESCC high-reliability thin film MINI-MELF resistors are the premium choice for design and manufacture of equipment, where matured technology and proven reliability are of utmost importance. They are regularly used in communication and research satellites and fit equally well into aircraft and military electronic systems.

Approval of the MS1 ESCC products is granted by the European Space Components Coordination and registered in the ESCC Qualified Parts List, REP005.
(www.vishay.com/doc?28790).

Notes

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents.

⁽²⁾ IEC 62474 database can be found at: <http://std.iec.ch/iec62474>.



FUNCTIONAL PERFORMANCE



Temperature Rise



Derating



Non-linearity



Current Noise - A_1



HF - Performance



HF - Performance



FUNCTIONAL PERFORMANCE



Single pulse high voltage overload capability
1.2/50 acc. EN 60115-1, 4.27



Single pulse high voltage overload capability
10/700 acc. EN 60115-1, 4.27



Single Pulse

Maximum pulse load, single pulse; applicable if $\bar{P} \rightarrow 0$ and $n \leq 1000$ and $\hat{U} \leq \hat{U}_{max}$; for permissible resistance change equivalent to 8000 h operation in power operation mode



Continuous Pulse

Maximum pulse load, continuous pulses; applicable if $\bar{P} \leq P(\vartheta_{amb})$ and $\hat{U} \leq \hat{U}_{max}$; for permissible resistance change equivalent to 8000 h operation in power operation mode



Pulse Voltage

TESTS AND REQUIREMENTS

All tests are carried out in accordance with the following specifications:

- EN 60115-1, generic specification
- EN 60115-8 (successor of EN 140400), sectional specification
- EN 140401-803, detail specification
- IEC 60068-2-xx, test methods

The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-803. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA/ECA-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

- Temperature: 15 °C to 35 °C
- Relative humidity: 45 % to 75 %
- Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

A climatic category LCT / UCT / 56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the damp heat, steady state test (56 days).

The components are mounted for testing on printed circuit boards in accordance with EN 60115-8, 2.4.2, unless otherwise specified.

TEST PROCEDURES AND REQUIREMENTS							
EN 60115-1 CLAUSE	IEC 60068-2 (1) TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)			
				< 1 Ω	1 Ω to < 10 Ω	10 Ω to \leq 1 M Ω	> 1 M Ω
4.8.4.2	-	Temperature coefficient (1)	At (20 / -55 / 20) °C and (20 / 125 / 20) °C	± 100 ppm/K, ± 50 ppm/K, ± 25 ppm/K, ± 15 ppm/K			
4.25.1	-	Endurance at 70 °C: precision operation mode	$U = \sqrt{P_{70} \times R} \leq U_{max}$ 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h			$\pm (0.05 \% R + 0.005 \Omega)$ $\pm (0.1 \% R + 0.005 \Omega)$	
		Endurance at 70 °C: standard operation mode	$U = \sqrt{P_{70} \times R} \leq U_{max}$ 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	$\pm (0.15 \% R + 0.01 \Omega)$ $\pm (0.3 \% R + 0.01 \Omega)$	$\pm (0.1 \% R + 0.005 \Omega)$ $\pm (0.2 \% R + 0.005 \Omega)$	$\pm (0.25 \% R)$ $\pm (0.5 \% R)$	



TEST PROCEDURES AND REQUIREMENTS							
EN 60115-1 CLAUSE	IEC 60068-2 (1) TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)			
				SMM0204	< 1 Ω	1 Ω to < 10 Ω	10 Ω to \leq 1 M Ω
4.25.1	-	Endurance at 70 °C: power operation mode	$U = \sqrt{P_{70} \times R}$ $\leq U_{max.}$; 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	$\pm (0.25 \% R + 0.01 \Omega)$ $\pm (0.5 \% R + 0.01 \Omega)$			
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h	$\pm (0.15 \% R + 0.01 \Omega)$	$\pm (0.1 \% R + 0.005 \Omega)$	$\pm (0.25 \% R)$	
			155 °C; 1000 h	$\pm (0.3 \% R + 0.01 \Omega)$	$\pm (0.2 \% R + 0.005 \Omega)$	$\pm (0.5 \% R)$	
4.24	78 (Cab)	Damp heat, steady state	(40 \pm 2) °C; 56 days; (93 \pm 3) % RH	$\pm (0.15 \% R + 0.01 \Omega)$			$\pm (0.25 \% R)$
4.39	67 (Cy)	Damp heat, steady state, accelerated	(85 \pm 2) °C (85 \pm 5) % RH $U = \sqrt{0.3 \times P_{70} \times R}$ ≤ 100 V and $U = 0.3 \times U_{max.}$; (the smaller value is valid) 1000 h	$\pm (0.25 \% R + 0.01 \Omega)$			$\pm (2 \% R)$
-	-	Cold	-55 °C; 2000 h	$\pm (0.1 \% R + 0.01 \Omega)$			
4.19	14 (Na)	Rapid change of temperature	30 min at LCT and 30 min at UCT; LCT = -55 °C; UCT = 125 °C; 1000 cycles	$\pm (0.15 \% R + 0.01 \Omega)$			$\pm (0.25 \% R)$
			LCT = -55 °C; UCT = 155 °C; 1000 cycles	$\pm (0.5 \% R + 0.01 \Omega)$			
4.13	-	Short time overload: standard operation mode	$U = 2.5 \times \sqrt{P_{70} \times R}$ $\leq 2 \times U_{max.}$; 5 s	$\pm (0.03 \% R + 0.01 \Omega)$			$\pm (0.1 \% R)$
		Short time overload: power operation mode		$\pm (0.05 \% R + 0.01 \Omega)$			$\pm (0.1 \% R)$
4.27	-	Single pulse high voltage overload: standard operation mode	Severity no. 4: $U = 10 \times \sqrt{P_{70} \times R}$ $\leq 2 \times U_{max.}$; 10 pulses 10 μ s/700 μ s	$\pm (0.15 \% R + 0.01 \Omega)$			
		Single pulse high voltage overload: power operation mode		$\pm (0.15 \% R + 0.01 \Omega)$			



TEST PROCEDURES AND REQUIREMENTS							
EN 60115-1 CLAUSE	IEC 60068-2 (1) TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)			
				SMM0204	< 1 Ω	1 Ω to < 10 Ω	10 Ω to \leq 1 M Ω
4.37	-	Periodic electric overload: standard operation mode	$U = \sqrt{15 \times P_{70} \times R}$ $\leq 2 \times U_{max.}$ 0.1 s on; 2.5 s off; 1000 cycles	$\pm (0.15 \% R + 0.01 \Omega)$			
		Periodic electric overload: power operation mode					
4.22	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude \leq 1.5 mm or \leq 200 m/s ² ; 7.5 h	$\pm (0.05 \% R + 0.01 \Omega)$			$\pm (0.1 \% R)$
4.38	-	Electrostatic discharge (Human Body Model)	IEC 61340-3-1 (1); 3 pos. + 3 neg. discharges SMM 0204: 2 kV	$\pm (0.5 \% R + 0.05 \Omega)$			
4.17.2	58 (Td)	Solderability	Solder bath method; SnPb40; non-activated flux (215 \pm 3) $^{\circ}$ C; (3 \pm 0.3) s	Good tinning (\geq 95% covered); no visible damage			
			Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux; (235 \pm 3) $^{\circ}$ C; (2 \pm 0.2) s	Good tinning (\geq 95% covered); no visible damage			
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method; (260 \pm 5) $^{\circ}$ C; (10 \pm 1) s	$\pm (0.1 \% R + 0.01 \Omega)$		$\pm (0.05 \% R + 0.01 \Omega)$	
			Reflow method 2 (IR/forced gas convection); (260 \pm 5) $^{\circ}$ C; (10 \pm 1) s	$\pm (0.05 \% R + 0.01 \Omega)$		$\pm (0.02 \% R + 0.01 \Omega)$	
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 $^{\circ}$ C; method 2	No visible damage			
4.30	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 $^{\circ}$ C; method 1, toothbrush	Marking visible, no visible damage			
4.32	21 (Ue ₃)	Shear (adhesion)	45 N	No visible damage			
4.33	21 (Ue ₁)	Substrate bending	Depth 2 mm, 3 times	No visible damage, no open circuit in bent position $\pm (0.05 \% + 0.005 \Omega)$			
4.7	-	Voltage proof	$U_{RMS} = U_{ins}$; 60 s	No flashover or breakdown			
4.35	-	Flammability	IEC 60695-11-5 (1); needle flame test; 10 s	No burning after 30s			

Note

(1) The quoted IEC standards are also released as EN standards with the same number and identical contents.

DIMENSIONS


DIMENSIONS AND MASS						
TYPE / SIZE	L (mm)	D (mm)	L ₁ min. (mm)	D ₁ (mm)	K (mm)	MASS (mg)
SMM0204 OMM0204	3.6 + 0/- 0.2	1.4 + 0/- 0.1	1.8	D + 0/- 0.15	0.8 ± 0.1	22

Notes

- Color code marking is applied according to IEC 60062 ⁽¹⁾ in four bands (E24 series) for 5 % tolerance, or in five bands (E96 or E192 series). Each color band appears as a single solid line, voids are permissible if at least 2/3 of the band is visible from each radial angle of view. The last color band for tolerance is approximately 50 % wider than the other bands.

PATTERN STYLES FOR MELF RESISTORS


RECOMMENDED SOLDER PAD DIMENSIONS								
TYPE / SIZE	WAVE SOLDERING				REFLOW SOLDERING			
	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)
SMM0204 OMM0204	1.5	1.5	1.8	4.5	1.7	1.2	1.6	4.1

Notes

- The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials may be required to maintain the reliability of the assembly. Specified power rating above standard operation mode requires dedicated heat-sink pads, which to a great extent depend on board materials and design. The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x ⁽¹⁾, or in publication IPC-7351. They do not guarantee any supposed thermal properties, particularly as these are also strongly influenced by many other parameters. Please note however that applications for "power operation mode" require special considerations for the design of solder pads and adjacent conductor areas.

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents.



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.